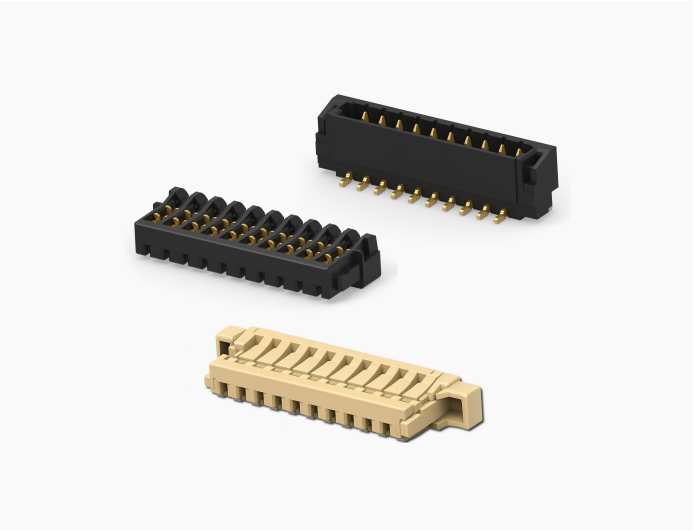
INTRODUCING

0.8MM LOW-PROFILE HPI CONNECTOR SYSTEM

- **Space-saving, low-profile design**
- **IDC and crimp cable termination options**
- **Helps save PCB real estate**



Meeting the industry need for small centerline wire-to-board connectors with convenient insulation displacement contact (IDC) or crimp termination options, 0.8 mm low-profile High Performance Interconnect (HPI) connectors can be used in space constrained applications where signal or low power needs to be routed through a device. TE offers an extensive wire-to-board product offering that provides customers with design flexibility and versatility. The 0.8mm low-profile IDC connector system is designed to enable product compatibility with industry standard products though square-peg technology to provide solutions to customers that extend past the design-in cycle.

APPLICATIONS

- **Internet of Things (IoT)**
  - Security systems
  - Small appliances
  - Smart meters
  - Vending machines
- **Data communications**
  - Servers
  - Switches
  - Modems
- **Consumer devices**
- **Automotive**
  - Control units
  - Infotainment systems
- **Medical**
  - Patient monitors
- **Industrial automation**

PRODUCT FEATURES

- Current rating: 1A
- High temperature plastic, UL94V-0
- Gold plating options available
- Compact 0.8mm centerline
- IDC and crimp cable terminations

LEARN MORE

- Landing Page
- Product Flyer

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